



Material Content Data Sheet



Sales Product Name		BSC070N10NS3 G		Issued		24. January 2018		
MA#		MA001599696						
Package		PG-TDSON-8-1		Weight*		121.71 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.666	3.01	3.01	30122	30122
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		93	
	non noble metal	iron	7439-89-6	0.038	0.03		311	
	non noble metal	copper	7440-50-8	37.762	31.03	31.07	310251	310655
	non noble metal	copper	7440-50-8	0.057	0.05	0.05	470	470
wire	non noble metal	copper	7440-50-8	0.057	0.05	0.05	470	470
encapsulation	organic material	carbon black	1333-86-4	0.081	0.07		667	
	plastics	epoxy resin	-	5.762	4.73		47345	
	inorganic material	silicondioxide	60676-86-0	34.737	28.54	33.34	285403	333415
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11927	11927
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1360	1360
solder	non noble metal	tin	7440-31-5	0.061	0.05		499	
	noble metal	silver	7440-22-4	0.076	0.06		624	
	non noble metal	lead	7439-92-1	2.899	2.38	2.49	23821	24944
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	iron	7439-89-6	0.011	0.01		93	
	non noble metal	copper	7440-50-8	11.320	9.30	9.31	93006	93127
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	iron	7439-89-6	0.022	0.02		183	
	noble metal	silver	7440-22-4	1.289	1.06		10594	
	non noble metal	copper	7440-50-8	22.292	18.31	19.40	183148	193980
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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